Data Sheet July 1999 File Number 4302.2

42A, 30V, 0.025 Ohm, Logic Level, N-Channel Power MOSFET

These are N-Channel power MOSFETs manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. These transistors can be operated directly from integrated circuits.

Formerly developmental type TA49030.

Ordering Information

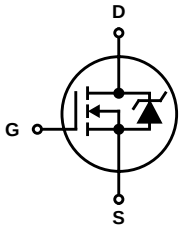
PART NUMBER	PACKAGE	BRAND
RFP42N03L	TO-220AB	FP42N03L
RF1S42N03LSM	TO-263AB	F42N03L

NOTE: When ordering, use the entire part number. Add the suffix, 9A, to obtain the TO-263AB variant in tape and reel, e.g., RF1S42N03LSM9A.

Features

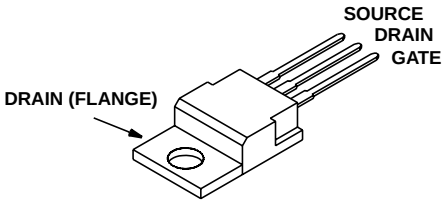
- 42A, 30V
- $r_{DS(ON)} = 0.025\Omega$
- Temperature Compensating PSPICE® Model
- Can be Driven Directly from CMOS, NMOS, and TTL Circuits
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- $175^{o}C$ Operating Temperature
- Related Literature
  - TB334 “Guidelines for Soldering Surface Mount Components to PC Boards”

Symbol

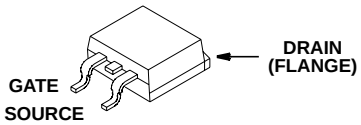


Packaging

JEDEC TO-220AB



JEDEC TO-263AB



Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

		RFP42N03L, RF1S42N03LSM	UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	30	V
Drain to Gate Voltage (R_{GS} = 20kΩ) (Note 1)	V_{DGR}	30	V
Gate to Source Voltage	V_{GS}	±10	V
Continuous Drain Current	I_D	42	A
Pulsed Drain Current (Note 3)	I_{DM}	Refer to Peak Current Curve	
Pulsed Avalanche Rating	E_{AS}	Refer to UIS Curve	
Power Dissipation	P_D	90	W
Derate Above 25^oC		0.606	$W/^oC$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175	^oC
Maximum Temperature for Soldering			
Leads at 0.063in (1.6mm) from Case for 10s	T_L	300	^oC
Package Body for 10s, See Techbrief 334	T_{pkg}	260	^oC

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^oC$ to 150^oC.

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	I_D = 250μA, V_{GS} = 0V		30	-	-	V
Gate to Source Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250μA		1	-	2	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = Rated BV_{DSS}, V_{GS} = 0V		-	-	1	μA
		V_{DS} = 0.8 x Rated BV_{DSS}, V_{GS} = 0V, $T_C = 150^oC$		-	-	25	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±10V		-	-	±100	nA
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	I_D = 42A, V_{GS} = 5V (Figure 11)		-	-	0.025	Ω
Turn-On Time	t_{ON}	V_{DD} = 15V, $I_D \approx$ 42A, R_L = 0.357Ω, V_{GS} = 5V, R_{GS} = 5Ω (Figures 10, 18, 19)		-	-	260	ns
Turn-On Delay Time	$t_{d(ON)}$			-	15	-	ns
Rise Time	t_r			-	160	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	20	-	ns
Fall Time	t_f			-	20	-	ns
Turn-Off Time	t_{OFF}			-	-	60	ns
Total Gate Charge	$Q_{g(TOT)}$	V_{GS} = 0V to 10V	V_{DD} = 24V, $I_D \approx$ 42A, R_L = 0.571Ω, $I_{G(REF)}$ = 0.6mA (Figures 15, 20, 21)	-	50	60	nC
Gate Charge at 5V	$Q_{g(5)}$	V_{GS} = 0V to 5V		-	30	36	nC
Threshold Gate Charge	$Q_{g(TH)}$	V_{GS} = 0V to 1V		-	1.5	1.8	nC
Input Capacitance	C_{ISS}	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz (Figure 14)		-	1650	-	pF
Output Capacitance	C_{OSS}			-	575	-	pF
Reverse Transfer Capacitance	C_{RSS}			-	200	-	pF
Thermal Resistance Junction-to-Case	$R_{\theta JC}$			-	-	1.65	$^oC/W$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$			-	-	80	$^oC/W$

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	I_{SD} = 42A	-	-	1.5	V
Diode Reverse Recovery Time	t_{rr}	I_{SD} = 42A, dI_{SD}/dt = 100A/μs	-	-	125	ns

NOTES:

2. Pulse test: pulse width ≤ 300μs, duty cycle ≤ 2%.
3. Repetitive rating: pulse width limited by Max junction temperature. See Transient Thermal Impedance curve (Figure 3).

Typical Performance Curves Unless Otherwise Specified

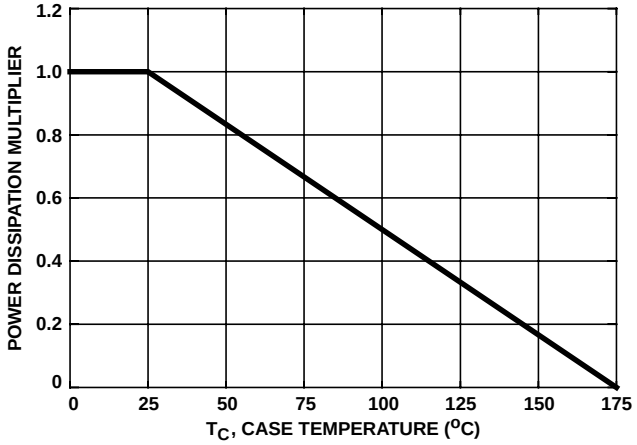


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

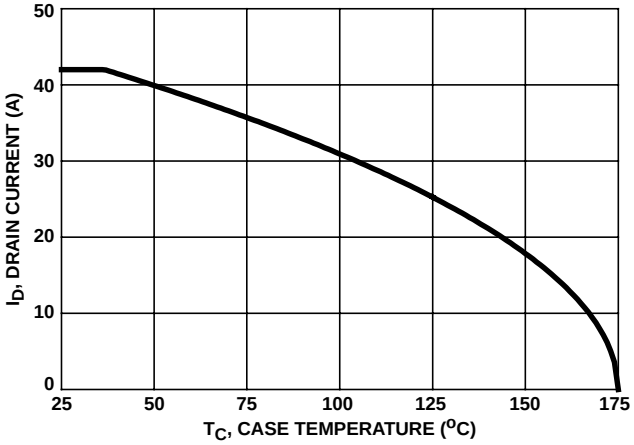


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

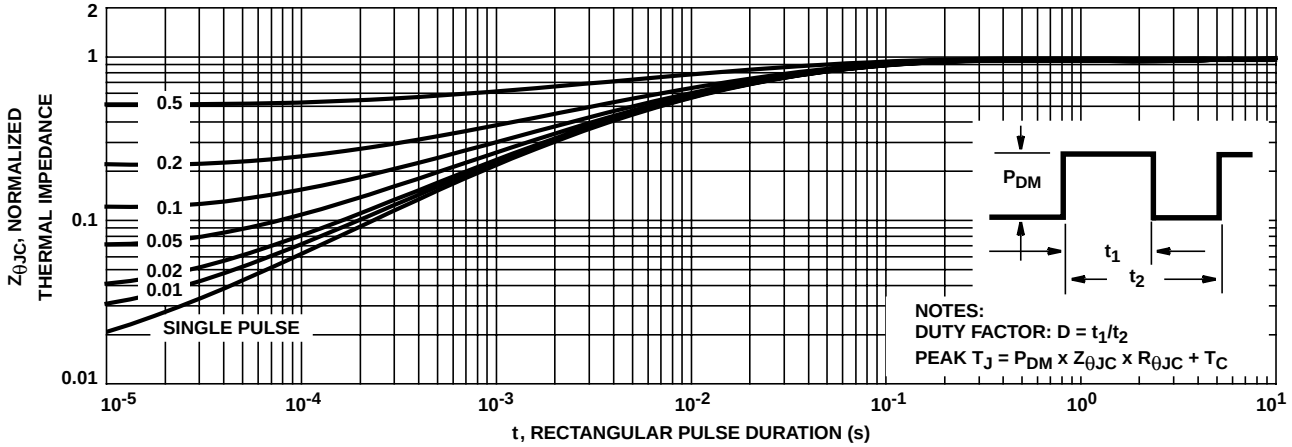


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

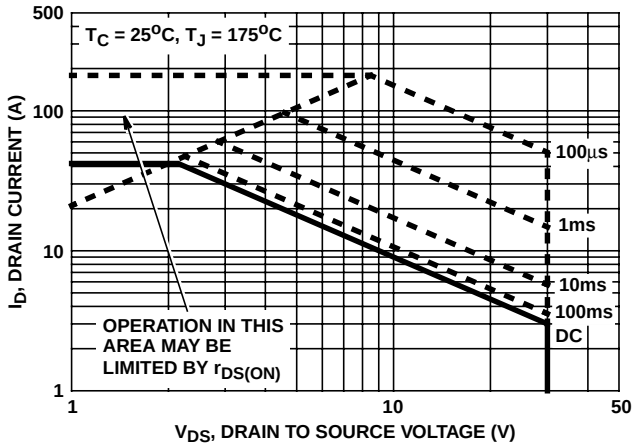


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

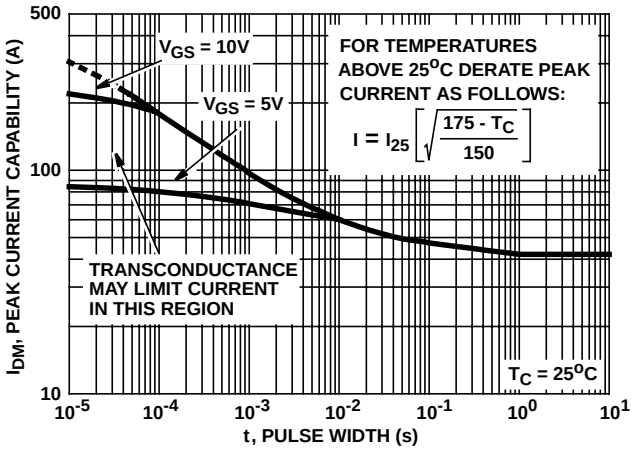
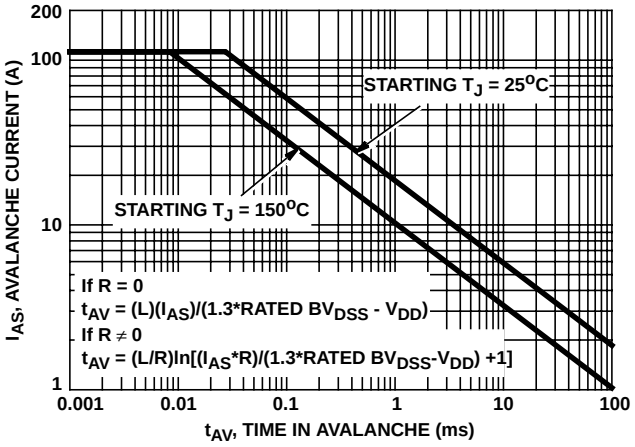


FIGURE 5. PEAK CURRENT CAPABILITY

Typical Performance Curves Unless Otherwise Specified (Continued)



NOTE: Refer to Intersil Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING

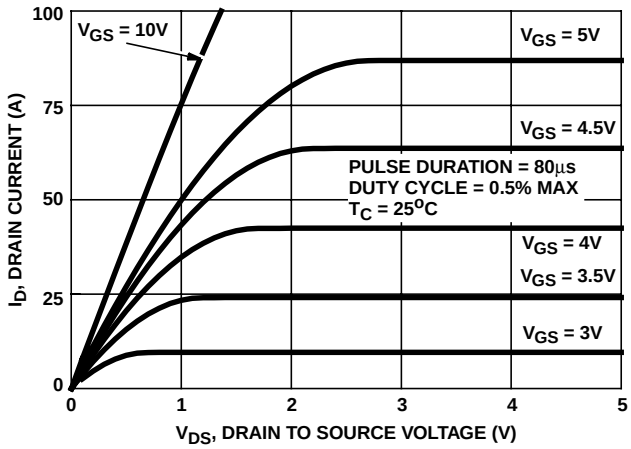


FIGURE 7. SATURATION CHARACTERISTICS

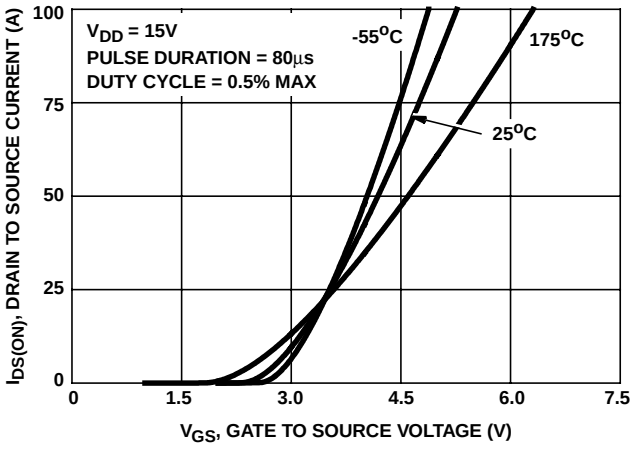


FIGURE 8. TRANSFER CHARACTERISTICS

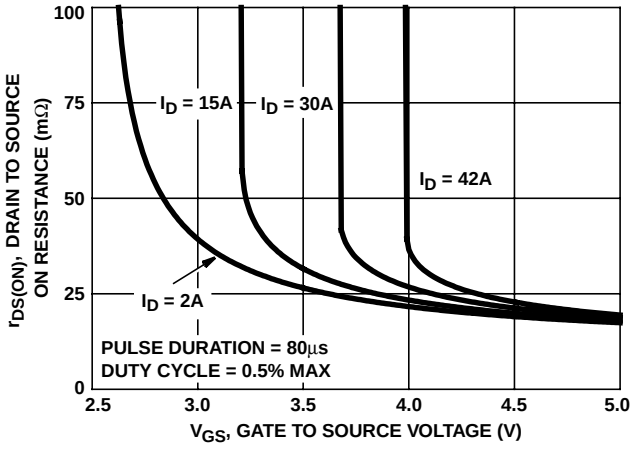


FIGURE 9. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

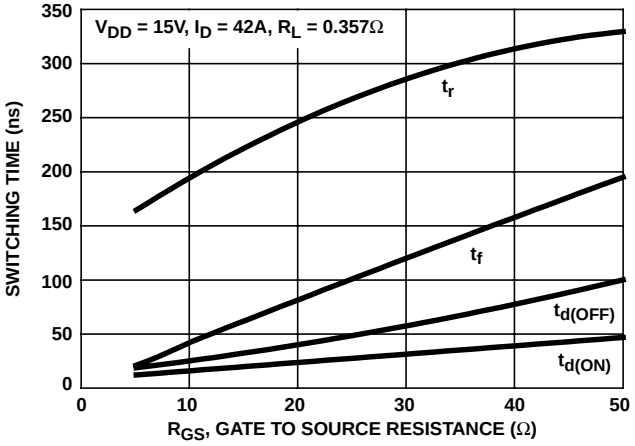


FIGURE 10. SWITCHING TIME vs GATE RESISTANCE

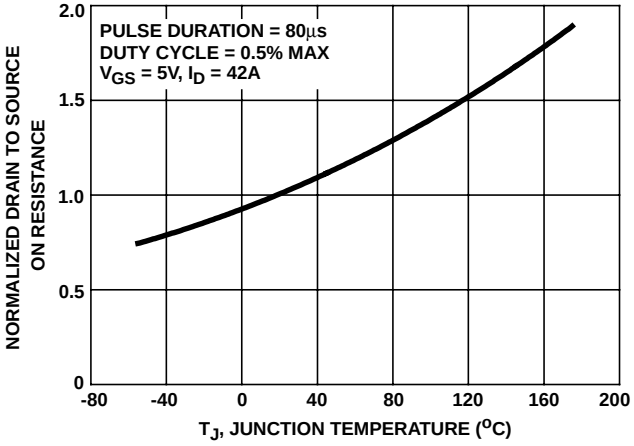


FIGURE 11. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified (Continued)

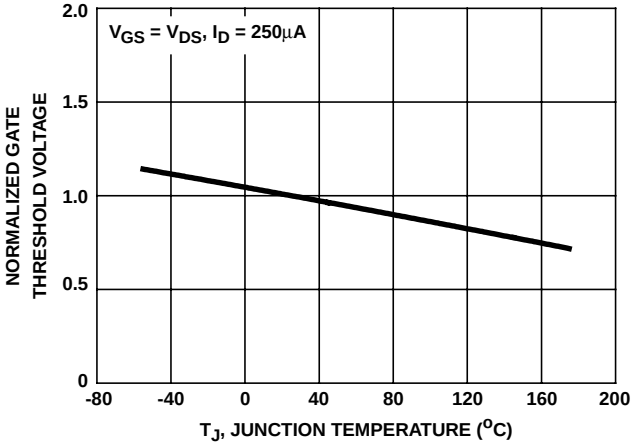


FIGURE 12. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

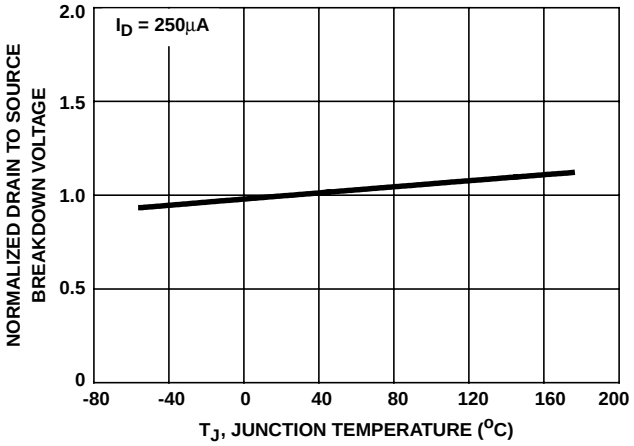


FIGURE 13. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

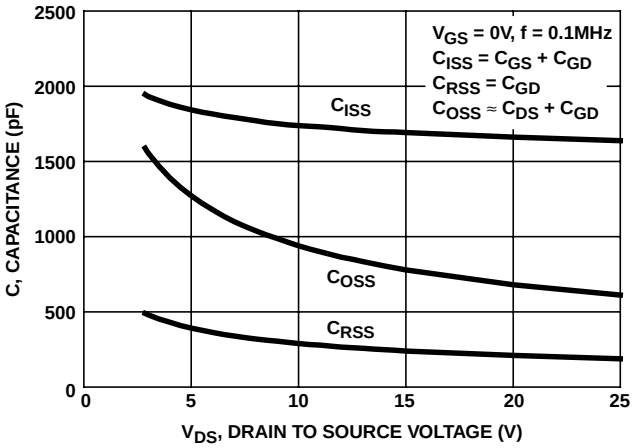
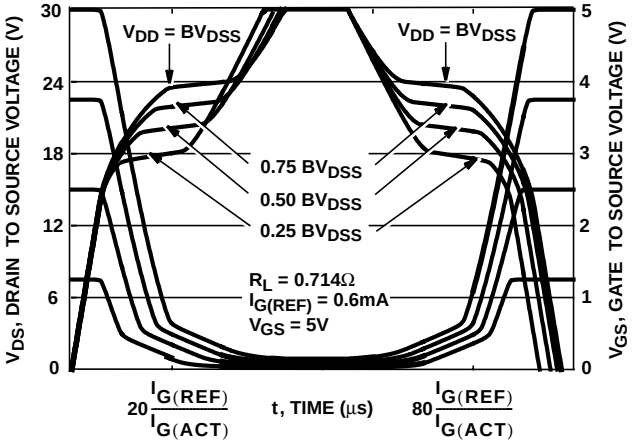


FIGURE 14. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Intersil Application Notes AN7254 and AN7260.

FIGURE 15. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

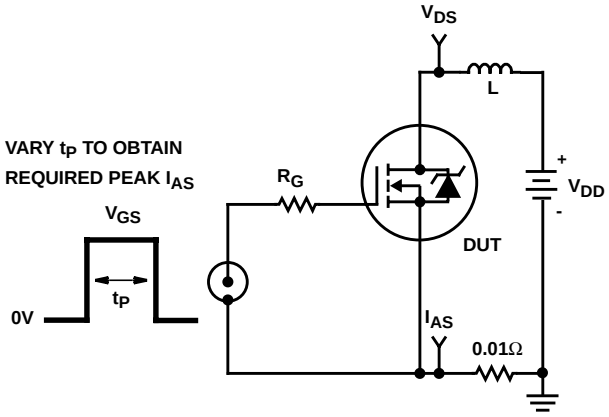


FIGURE 16. UNCLAMPED ENERGY TEST CIRCUIT

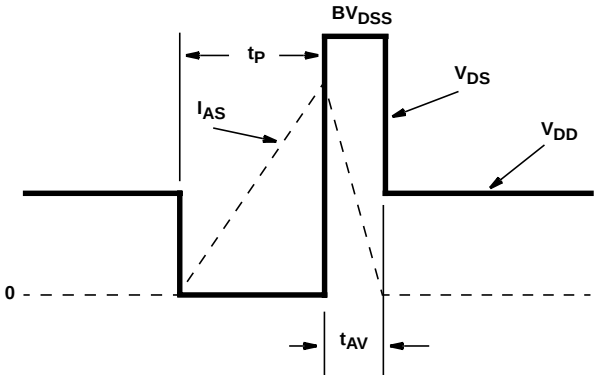


FIGURE 17. UNCLAMPED ENERGY WAVEFORMS

Test Circuits and Waveforms (Continued)

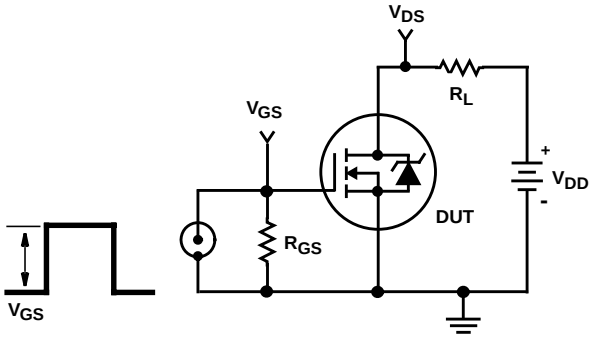


FIGURE 18. SWITCHING TIME TEST CIRCUIT

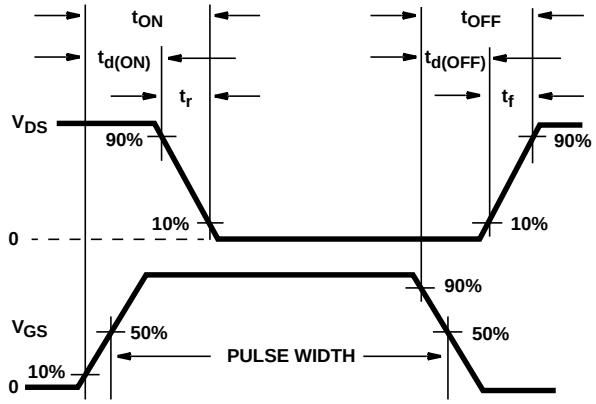


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

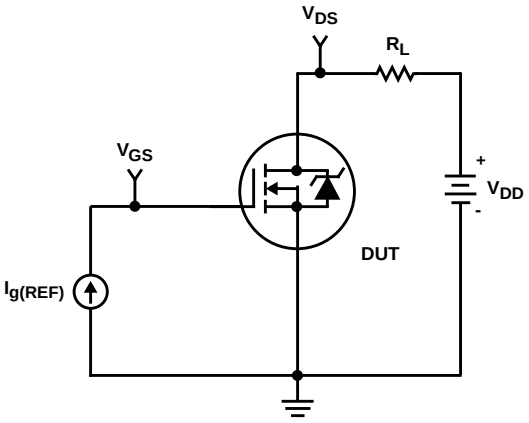


FIGURE 20. GATE CHARGE TEST CIRCUIT

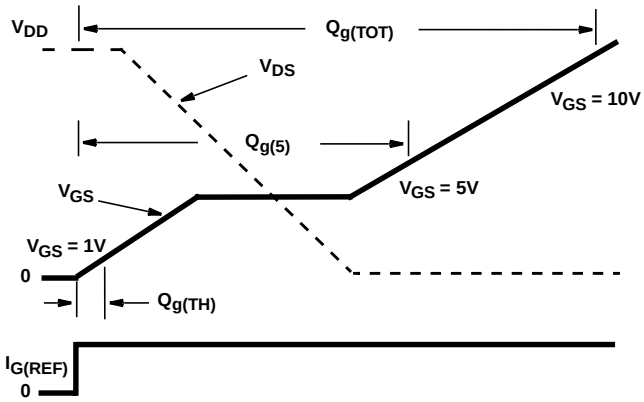


FIGURE 21. GATE CHARGE WAVEFORMS

PSPICE Electrical Model

.SUBCKT RFP42N03L 2 1 3 ; rev 12/24/96

CA 12 8 2.55e-9
CB 15 14 2.64e-9
CIN 6 8 1.45e-9

DBODY 7 5 DBDMOD
DBREAK 5 11 DBKMOD
DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 33.3
EDS 14 8 5 8 1
EGS 13 8 6 8 1
ESG 6 10 6 8 1
EVTO 20 6 18 8 1

IT 8 17 1

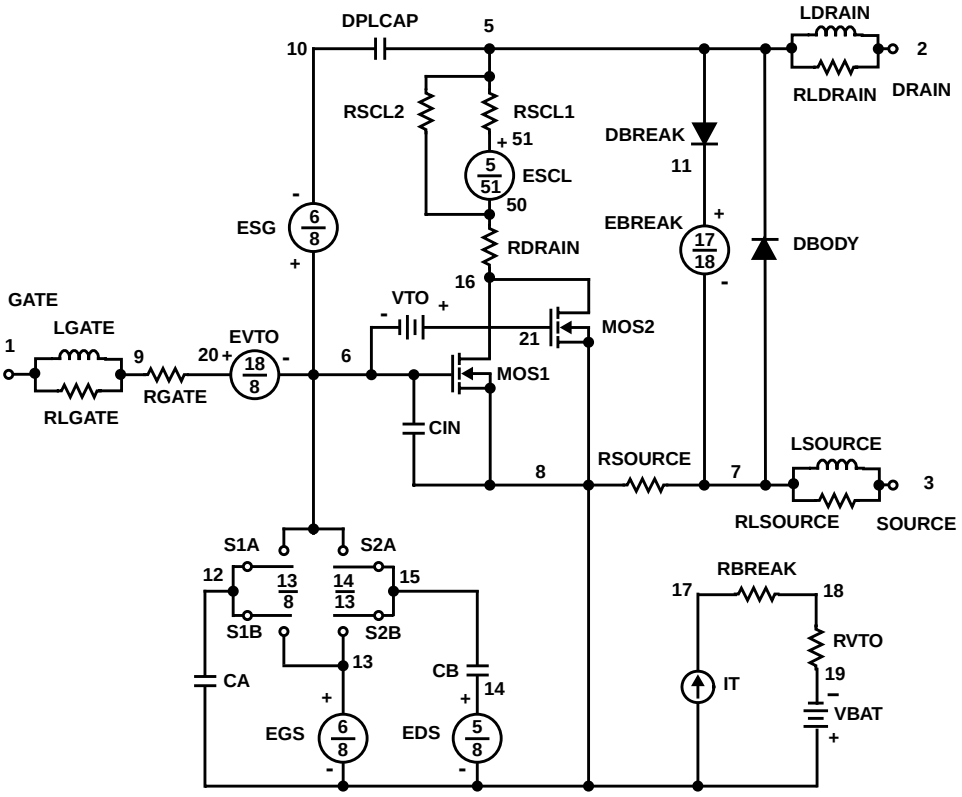
LDRAIN 2 5 1e-9
LGATE 1 9 4.9e-9
LSOURCE 3 7 4.9e-9

MOS1 16 6 8 8 MOSMOD M = 0.99
MOS2 16 21 8 8 MOSMOD M = 0.01

RBREAK 17 18 RBKMOD 1
RDRAIN 50 16 RDSMOD 0.14e-3
RGATE 9 20 0.89
RLDRAIN 2 5 10
RLGATE 1 9 49
RLSOURCE 3 7 49
RSCL1 5 51 RSCLMOD 1e-6
RSCL2 5 50 1e3
RSOURCE 8 7 RDSMOD 10.31e-3
RVTO 18 19 RVTOMOD 1

S1A 6 12 13 8 S1AMOD
S1B 13 12 13 8 S1BMOD
S2A 6 15 14 13 S2AMOD
S2B 13 15 14 13 S2BMOD

VBAT 8 19 DC 1
VTO 21 6 0.583



ESCL 51 50 VALUE = {(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)*1e6/176,6))}

.MODEL DBDMOD D (IS = 3.61e-13 RS = 5.06e-3 TRS1 = 3.05e-3 TRS2 = 7.57e-6 CJO = 2.16e-9 TT = 2.18e-8)
.MODEL DBKMOD D (RS = 1.66e-1 TRS1 = -2.97e-3 TRS2 = 7.57e-6)
.MODEL DPLCAPMOD D (CJO = 0.96e-9 IS = 1e-30 N = 10)
.MODEL MOSMOD NMOS (VTO = 2.313 KP = 53.82 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)
.MODEL RBKMOD RES (TC1 = 8.95e-4 TC2 = -1e-7)
.MODEL RDSMOD RES (TC1 = 3.82e-3 TC2 = 1.17e-5)
.MODEL RSCLMOD RES (TC1 = 2.03e-3 TC2 = 0.45e-5)
.MODEL RVTOMOD RES (TC1 = -2.27e-3 TC2 = -5.75e-7)
.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -4.82 VOFF= -2.82)
.MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -2.82 VOFF= -4.82)
.MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -2.67 VOFF= 2.33)
.MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 2.33 VOFF= -2.67)

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; written by William J. Hepp and C. Frank Wheatley.

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